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Dated: April 10, 2002 Signature: MJDoherty (Michael J. Doherty)

Docket No.: TESSERA 3.0-109 CIP DIV (PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kim et al.

Application No.: 09/776,356 Group Art Unit: 2814

Filed: February 2, 2001 Examiner: Not Yet Assigned

For: STACKED MICROELECTRONIC ASSEMBLY AND METHOD THEREFOR

Commissioner for Patents
Washington, DC 20231

PRELIMINARY AMENDMENT

Dear Sir:

Preliminary to initiation of the prosecution of the above-identified pending U.S. patent application, the following amendments and remarks are respectfully submitted.

IN THE CLAIMS

Please add new claims 9-20.

A1

9. A method of making a stacked microelectronic assembly comprising:

providing a flexible substrate including a plurality of attachment sites, said flexible substrate having a first surface, a second surface opposite said first surface, first electrical contacts accessible at at least one of said first and second surfaces, second electrical contacts accessible at at least one of said first and second surfaces, wiring connected to said first and

1. Cont'd.

second electrical contacts, and flexible leads extending to said attachment sites;

assembling microelectronic elements to said attachment sites;

electrically connecting said microelectronic elements to said flexible leads;

folding said flexible substrate into a folded configuration so that said first electrical contacts are accessible at a bottom of said microelectronic assembly and said second electrical contacts are accessible at a top of said microelectronic assembly; and

maintaining said flexible substrate in the folded configuration.

10. The method as claimed in claim 9, wherein said first electrical contacts are electrically conductive terminals and said second electrical contacts are test contacts.

11. The method as claimed in claim 10, wherein said test contacts are exposed at the top of said microelectronic assembly.

12. The method as claimed in claim 10, wherein said conductive terminals and at least some of said test contacts are accessible at the second surface of said flexible substrate.

13. The method as claimed in claim 11, wherein at least some of said test contacts are accessible at the first surface of said flexible substrate.

14. The method as claimed in claim 9, further comprising:

A' Cont'd.

disposing a curable liquid encapsulant composition between at least one of said microelectronic elements and said flexible substrate; and

curing said curable liquid encapsulant composition to form a compliant layer.

15. A method of making a microelectronic assembly, comprising the steps of:

providing a flexible substrate have at least one attachment site, said flexible substrate including a first surface and a second surface and having a plurality of first electrical contacts accessible at at least one of said first and second surfaces, second electrical contacts accessible at at least one of said first and second surfaces, wiring connected to said first and second electrical contacts, and flexible leads extending to said at least one attachment site;

assembling a microelectronic element to said at least one attachment site;

electrically connecting a microelectronic element to said flexible leads;

folding said flexible substrate into a folded configuration having a folded portion; and

maintaining said flexible substrate in the folded configuration, wherein said first electrical contacts are exposed at a bottom end of said microelectronic assembly and said second electrical contacts are exposed at a top end of said microelectronic assembly.

16. The method as claimed in claim 15, wherein said first electrical contacts are electrically conductive terminals and said second electrical contacts are test contacts.

A' Cont'd.

17. The method as claimed in claim 16, wherein said conductive terminals are accessible at the second surface of said flexible substrate and at least some of said test contacts are accessible at the second surface of said flexible substrate.

18. The method as claimed in claim 15, wherein at least some of said test contacts are accessible at the first surface of said flexible substrate.

19. The method as claimed in claim 15, further comprising:

disposing a curable liquid encapsulant composition between said microelectronic element and said flexible substrate; and

curing said curable liquid encapsulant composition to form a compliant layer.

20. The method as claimed in claim 15, further comprising:

attaching a second microelectronic element to said flexible substrate;

vertically aligning the first and second microelectronic elements with one another during the folding step.

REMARKS

The above-noted addition of new claims 9-20 are respectfully submitted prior to initiation of the prosecution of this application in the U.S. Patent and Trademark Office. The above-noted new claims are respectfully submitted in order to more clearly and appropriately claim the subject matter which Applicants consider to constitute their inventive contribution. No new matter is included in these amendments.

In view of the above, it is respectfully requested that these amendments now be entered, and that prosecution on the merits of this application now be initiated. If, however, for any reason the Examiner does not believe such action can be taken, it is respectfully requested that he telephone Applicants' attorney at (908) 654-5000 in order to overcome any objections which he may have.

If there are any additional charges in connection with this requested amendment, the Examiner is authorized to charge Applicants' Deposit Account No. 12-1095 therefor.

Dated: April 10, 2002

Respectfully submitted,

By Michael J. Doherty

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